

CHEMICAL MECHANICAL POLISHING ENDPOINT DETECTION SYSTEM AND  
METHOD

ABSTRACT

5       The system includes a polishing pad, a pad height sensor; a window; and a  
window raising mechanism. The polishing pad has an aperture with the window  
vertically moveable therein. The pad height sensor is positioned above the polishing pad  
and measures the vertical position of the pad before polishing. The window raising  
mechanism adjusts the vertical position of the window based on information from the pad  
10   height sensor. An endpoint measurement sensor can be disposed beneath the window for  
in-situ measurement of the polishing process.